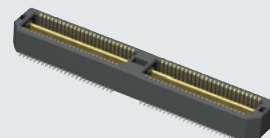
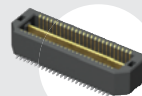


QTS-075-01-F-D-A

QTS-025-01-L-D-A



QTS-050-01-F-D-A

(0,635 mm) .025"

QTS SERIES

# HIGH SPEED GROUND PLANE HEADER

## SPECIFICATIONS

For complete specifications and recommended PCB layouts see [www.samtec.com?QTS](http://www.samtec.com?QTS)

### Insulator Material:

Liquid Crystal Polymer

### Contact Material:

Phosphor Bronze

### Plating:

Au or Sn over

50µ" (1,27 µm) Ni

### Current Rating:

Contact:

1.8 A per pin

(1 pin powered per row)

Ground Plane:

23.1 A per ground plane

(1 ground plane powered)

### Operating Temp:

-55°C to +125°C

### Voltage Rating:

285 VAC

### Max Cycles:

100

### RoHS Compliant:

Yes

### Processing:

Lead-Free Solderable: Yes

SMT Lead Coplanarity:

(0,10 mm) .004" max (025-075)

### Board Stacking:

For applications requiring more

than two connectors per board

contact [ipg@samtec.com](mailto:ipg@samtec.com)

### Board Mates:

QSS

### Cable Mates:

SCQD

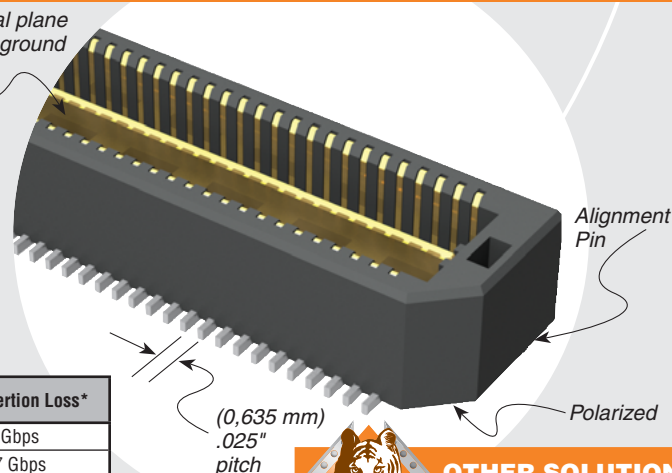


| QTS/QSS<br>5 mm Stack Height | Type | Rated @ 3dB Insertion Loss* |
|------------------------------|------|-----------------------------|
| Single-Ended Signaling       | -D   | 9 GHz / 18 Gbps             |
| Differential Pair Signaling  | -D   | 8.5 GHz / 17 Gbps           |
| Differential Pair Signaling  | -DP  | 8.5 GHz / 17 Gbps           |

\*Performance data includes effects of a non-optimized PCB.

Performance data for other stack heights and complete test data available at [www.samtec.com?QTS](http://www.samtec.com?QTS) or contact [sig@samtec.com](mailto:sig@samtec.com)

Integral metal plane  
for power or ground



(0,635 mm)  
.025"  
pitch

Alignment  
Pin

Polarized



## OTHER SOLUTIONS

• Board spacing  
standoffs  
(See SO Series)

## RECOGNITIONS

For complete scope  
of recognitions see  
[www.samtec.com/quality](http://www.samtec.com/quality)



FILE NO. E111594

## ALSO AVAILABLE (MOQ Required)

- 11 mm & 16 mm stack height (Caution: Some automatic placement/inspection machines may have component height restrictions. Please consult machinery specifications.)
- 30µ" (0,76 µm) Gold
- Differential Pair and "Partitionable" (combine differential & single-ended banks in same connector) available.
- 100 & 125 positions per row
- Edge Mount

Contact Samtec.

\*Note: -C Plating passes  
10 year MFG testing

Note: Some lengths, styles  
and options are non-standard,  
non-returnable.

| QTS | NO. OF POSITIONS<br>PER ROW | LEAD<br>STYLE | PLATING<br>OPTION | D | A | OTHER<br>OPTION |
|-----|-----------------------------|---------------|-------------------|---|---|-----------------|
|-----|-----------------------------|---------------|-------------------|---|---|-----------------|

-025, -050, -075  
(50 total positions per bank)

Specify  
LEAD  
STYLE  
from  
chart.

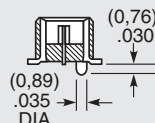
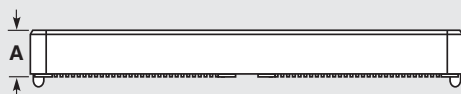
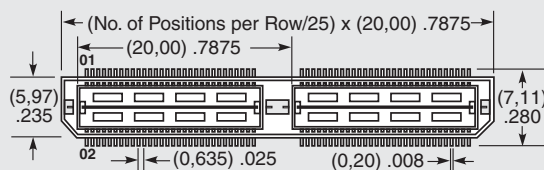
-F  
= Gold Flash on Signal Pins  
and Ground Plane,  
Matte Tin on tails

-L  
= 10µ" (0,25 µm) Gold on Signal  
Pins and Ground Plane,  
Matte Tin on tails

-C\*  
= Electro-Polished Selective  
50µ" (1,27 µm) min Au over  
150µ" (3,81 µm) Ni on Signal  
Pins in contact area,  
10µ" (0,25 µm) min Au over  
50µ" (1,27 µm) Ni on Ground  
Plane in contact area,  
Matte Tin over 50µ" (1,27 µm)  
min Ni on all solder tails

-K  
= (7,00 mm)  
.275" DIA  
Polyimide film  
Pick &  
Place Pad

-TR  
= Tape & Reel



| STACK HEIGHTS |             |                 |
|---------------|-------------|-----------------|
| LEAD<br>STYLE | A           | MATED<br>HEIGHT |
| -01           | (4,27) .168 | (5,00) .197     |
| -02           | (7,26) .286 | (8,00) .315     |

Processing conditions will  
affect mated height.